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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)			
	10/563,931	LIFKA ET AL.			
Office Action Summary	Examiner	Art Unit			
	Aaron Williams	2889			
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address			
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim vill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONEI	Lely filed the mailing date of this communication. (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on <u>09 Ja</u>	action is non-final. nce except for formal matters, pro				
Disposition of Claims					
4) Claim(s) 1-28 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 1-28 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or Application Papers 9) The specification is objected to by the Examinet 10) The drawing(s) filed on is/are: a) access applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction.	vn from consideration. r election requirement. r. epted or b) □ objected to by the Edrawing(s) be held in abeyance. See	e 37 CFR 1.85(a).			
11)☐ The oath or declaration is objected to by the Ex	aminer. Note the attached Office	Action or form PTO-152.			
Priority under 35 U.S.C. § 119					
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date 4/12/2007, 1/9/2006.	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ite			

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DETAILED ACTION

Priority

1. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 3. Claims 1-12, 20-28 are rejected under 35 U.S.C. 102(b) as being anticipated by US Patent 6,570,325 to Graff et al., herein refer to as Graff.

Regarding claim 1, Graff discloses an encapsulation structure (Figure 1, first barrier stack (115), refer to paragraph [0026]) for a display device, comprising a dielectric sealing structure (3) (figure 1, first barrier layer (130), refer to paragraph [0034]), characterized in that the encapsulation structure also comprises a stabilisation layer (5) (Figure 1, first decoupling layer (125), paragraph [0041]).

Regarding claim 2, Graff discloses an encapsulation structure according to claim 1, wherein said stabilisation layer (5) (decoupling layer (125)) is of a polymeric material refer to paragraph [0043].

Regarding claim 3, Graff discloses an encapsulation structure according to claim 1, wherein said sealing structure (3) (Figure 3, first barrier stack (315),(320)) comprises a first layer (6) (Figure 3, first barrier layer (345)) of a first dielectric material and a

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second layer (7) (Figure 3, first barrier layer (360)) of a second dielectric material. Refer to paragraph [0034] where Graff disclose the first barrier layer can be composed of the same or different material and list the material that make up the layers composition.

Regarding claim 4, Graff discloses an encapsulation structure according to claim 3, wherein said sealing structure (3) (Figure 3, first barrier stacks (315), (320)) comprises a third layer (8) (Figure 3, first barrier layer (365)) of a third dielectric material. Refer to paragraph [0034] where Graff disclose the first barrier layer can be composed of the same or different material and list the material that make up the layers composition.

Regarding claim 5, Graff discloses an encapsulation structure according to claim 4, wherein said third dielectric material is the same as said first dielectric material.

Refer to paragraph [0034] where Graff disclose the first barrier layer can be composed of the same or different material and list the material that make up the layers composition.

Regarding claim 6, Graff discloses an encapsulation structure according to claim 3, wherein said first dielectric material is selected from the group comprising silicon nitride, aluminum nitride and any mixture thereof, and wherein said second dielectric material is selected from the group comprising silicon oxide, silicon oxide fluoride, titanium oxide, tantalum oxide, zirconium oxide, hafnium oxide, aluminium oxide and any mixture thereof. Refer to paragraph [0034] where Graff disclose the first barrier layer can be composed of the same or different material and list the material that make up the layers composition.

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Regarding claim 7, Graff discloses an encapsulation structure according to claim 3, wherein said first dielectric material is selected from the group comprising silicon oxide, silicon oxide fluoride, titanium oxide, tantalum oxide, zirconium oxide, hafnium oxide, aluminium oxide and any mixture thereof, and wherein said second dielectric material is selected from the group comprising silicon nitride, aluminium nitride and any mixture thereof. Refer to paragraph [0034] where Graff disclose the first barrier layer can be composed of the same or different material and list the material that make up the layers composition.

Regarding claim 8, Graff discloses an encapsulation structure according to claim 1, wherein said stabilisation layer (5) (Figure 1, first decoupling layer (125), paragraph [0041]) covers at least some protruding structures (4) (Defects in layer or organic light emitting device (not shown)) of said display device, and forms an essentially planar surface over said protruding structures (4). Refer to paragraph [0041] for details how the decoupling layer reduces surface imperfections.

Regarding claim 9, Graff discloses an encapsulation structure according to claim 1, wherein an essentially cavity-free interface is formed between said stabilisation layer (5) (decoupling layer (125)) and said sealing structure (3) (first barrier layer (130)).

Regarding claim 10, Graff discloses an encapsulation structure according to claim 1, wherein the thermal expansion coefficient of said stabilisation layer (5) (decoupling layer (125)) is essentially the same as the thermal expansion coefficient of said sealing structure (3) (first barrier layer (130)). Since the materials are anticipated the limitations of claim 10 are anticipated.

Regarding claim 11, Graff discloses an encapsulation structure according to claim 1, wherein the thickness of said stabilisation layer (5) (decoupling layer (125)) is at least 0.1 µm refer to paragraph [0027] where the thickness range is 0.1-1.0 µm.

Regarding claim 12 Graff discloses an encapsulation structure according to claim 1, wherein said encapsulation structure is transparent. Refer to paragraph [0036] where Graff defines transparent greater then 40% transmission of visible light.

Regarding claim 20, Graff discloses an encapsulation structure according to claim 1, wherein said display device is selected from a polyLED display, a OLED display (OLED (200)) or a Liquid Crystal Display. Refer to paragraph [0030].

Regarding claim 22, Graff discloses a method for the manufacture of an encapsulation structure for a display device comprising depositing a dielectric sealing structure (3) (Figure 1, first barrier layer (130), refer to paragraph [0035]), and depositing a stabilisation layer (5) (Figure 1, first decoupling layer (125), paragraph [0042]).

Regarding claim 23, Graff discloses a method according to claim 22, wherein said depositing of a stabilisation layer (5) (decoupling layer (125)) comprises depositing a curable composition, and curing said curable composition refer to paragraph [0043].

Regarding claim 24, Graff discloses a method according to claim 23, wherein said curing is thermal curing refer to paragraph [0043].

Regarding claim 25, Graff discloses a method according to claim 22 wherein said stabilisation layer (5) (decoupling layer (125)) is deposited by inkjet printing refer to paragraph [0042].

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Regarding claim 26, Graff discloses a method according to claim 22 wherein said display device is selected from a polyLED display, an OLED display (OLED (200)) and a LCD display. Refer to paragraph [0030].

Regarding claim 27, Graff discloses a display device (OLED (200)) comprising an encapsulation structure according to claim 1. Refer to paragraph [0030].

Regarding claim 28, Graff discloses a display device (OLED (200)) obtainable by the method according to claim 22. Refer to paragraph [0030].

4. Claims 1, 13-19, 21 are rejected under 35 U.S.C. 102(b) as being anticipated by US Patent Grant Publication 2003/0003225 by Choi et al., herein refer to as Choi.

Regarding claim 1, Choi discloses an encapsulation for a display device, comprising a dielectric sealing structure (3) (figure 2, passivation layer (130), refer to paragraph [0027]), characterized in that the encapsulation structure also comprises a stabilisation layer (5) (Figure 2, high-density uniform layer (131), paragraph [0049]).

Regarding claim 13, Choi discloses an encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) of according to claim 1, wherein said stabilisation layer (5) (Figure 2, high-density uniform layer (131), paragraph [0049]) is of a non-polymeric material (paragraph [0049] describes the high-density uniform layer (131) is formed of silicon and nitrogen).

Regarding claim 14, Choi discloses an encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) according to claim 13, wherein said non-polymeric material is a cured inorganic material (paragraphs [0045] -

[0049] describes the passivation layer (130) and high-density uniform layer (131) is formed of annealing inorganic silicon and nitrogen).

Regarding claim 15, Choi discloses an encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) according to claim 13, wherein said stabilisation layer (5) (high-density uniform layer (131)) covers at least some protruding structures (4) (Figure 2 structures of layers (112)-(118), paragraph [0027]) of said display device and forms an essentially planar surface (Figure 2 shows a planar surface) over said covered protruding structures (Figure 2 structures of layers (112)-(118), paragraph [0027]).

Regarding claim 16, Choi discloses an encapsulation structure according to claim 13, wherein an essentially cavity-free interface is formed between said stabilisation layer (5) (high-density uniform layer (131)) and said sealing structure (3) (passivation layer (130)).

Regarding claim 17, Choi discloses an encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) according to claim 13, wherein the thermal expansion coefficient of said stabilisation layer (5) (high-density uniform layer (131)) is essentially the same as the thermal expansion coefficient of said sealing structure (3) (passivation layer (130)). Since the materials of the two layers are made of essentially the same material it is inherent that thermal expansion coefficient is essentially the same.

Regarding claim 18, Choi discloses an encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) according to claim 13,

wherein the thickness of said stabilisation layer (5) (high-density uniform layer (131)) is at least 0.1 µm refer to paragraph [0049] where the thickness range is 0.001-1.0 µm.

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Regarding claim 19, Choi discloses an encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) according to claim 13, wherein said encapsulation structure (The combination passivation layer (130) and high-density uniform layer (131)) is transparent. Since the materials anticipated the features of the materials are anticipated too.

Regarding claim 21, Choi discloses an encapsulation structure according to claim 1, wherein said display device comprises protruding structures (4) (Figure 2 structures of layers (112)-(118), paragraph [0027]) with negative slopes which forms shadow regions. Refer to figure 2.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Aaron Williams whose telephone number is (571) 270-5279. The examiner can normally be reached on Monday thru Friday 7:00 to 5:00 EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Toan Ton can be reached on (571)272-2303. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Aaron Williams/ Examiner, Art Unit 2889

/Karabi Guharay/ Primary Examiner, Art Unit 2889